L Number	Hits	Search Text	DB	Time stamp
7	122	('STI' 'FOX' 'LOCOS' shallow adj trench) with (glue adhesi$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 13:08
8	4430	('STI' 'FOX' 'LOCOS' shallow adj trench) with (opening cave hollow recess groove gap hole via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 13:10
10	396	(('STI' 'FOX' 'LOCOS' shallow adj trench) with (opening cave hollow recess groove gap hole via)) and ('STI' 'FOX' 'LOCOS' shallow adj trench) with (bird near3 beak)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 13:13
11	3	((('STI' 'FOX' 'LOCOS' shallow adj trench) with (opening cave hollow recess groove gap hole via)) and ('STI' 'FOX' 'LOCOS' shallow adj trench) with (bird near3 beak)) and ('STI' 'FOX' 'LOCOS' shallow adj trench) with (glue adhes$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 15:24
12	31	"5683924"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 13:16
13	1		USPAT	2004/11/02 13:17
14	1		USPAT	2004/11/02 15:33
19	5	"6307251"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 15:31
20	3	"6294823"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 15:26
21	13	"5930620"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 15:28
22	9	"6124627"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 15:29
23	7	"6127233"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 15:31
24	1	("5683924").PN.	USPAT; US-PGPUB; EPO; JPO	2004/11/02 15:34
25	1		USPAT	2004/11/02 15:34
26	1		USPAT	2004/11/02 15:34
27	1		USPAT	2004/11/02 15:35
28	1		USPAT	2004/11/02 15:35
29	1		USPAT	2004/11/02 15:35
30	1		USPAT	2004/11/02 15:35
31	1		USPAT	2004/11/02 15:38
32	1		USPAT	2004/11/02 15:38

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33	1		USPAT	2004/11/02 15:38
34	1		USPAT	2004/11/02 15:38
35	1		USPAT	2004/11/02 15:39
36	1		USPAT	2004/11/02 15:50
37	1		USPAT	2004/11/02 15:50
38	1		USPAT	2004/11/02 15:51
-	4799	('STI' 'FOX' 'LOCOS' isolat$3) with (glue adhesi$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 13:06
-	214	(('STI' 'FOX' 'LOCOS' isolat$3) with (glue adhesi$3)) and ((first second) near3 type)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 12:10
-	178	((('STI' 'FOX' 'LOCOS' isolat$3) with (glue adhesi$3)) and ((first second) near3 type)) and (trench opening groove hole via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:03
-	122	(((('STI' 'FOX' 'LOCOS' isolat$3) with (glue adhesi$3)) and ((first second) near3 type)) and (trench opening groove hole via)) and (dielectric insulat$3 conducti$3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:03
-	117	((((('STI' 'FOX' 'LOCOS' isolat$3) with (glue adhesi$3)) and ((first second) near3 type)) and (trench opening groove hole via)) and (dielectric insulat$3 conducti$3 etch$3)) and (metal silicide heat$3 anneal$3 thermal$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:03
-	1	shallow adj trench adj isolator.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:02
-	1103	shallow adj trench adj isolat$3.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:02
-	1103	(shallow adj trench adj isolat$3.ti.) and (trench opening groove hole via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:03
-	923	((shallow adj trench adj isolat$3.ti.) and (trench opening groove hole via)) and (dielectric insulat$3 conducti$3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:03
-	502	(((shallow adj trench adj isolat$3.ti.) and (trench opening groove hole via)) and (dielectric insulat$3 conducti$3 etch$3)) and (metal silicide heat$3 anneal$3 thermal$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:04
-	112	((((shallow adj trench adj isolat$3.ti.) and (trench opening groove hole via)) and (dielectric insulat$3 conducti$3 etch$3)) and (metal silicide heat$3 anneal$3 thermal$3)) and (P adj type N adj type first near3 type second near3 type)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:06

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-	45	(((((shallow adj trench adj isolat$3.ti.) and (trench opening groove hole via)) and (dielectric insulat$3 conducti$3 etch$3)) and (metal silicide heat$3 anneal$3 thermal$3)) and (P adj type N adj type first near3 type second near3 type)) and ((glue stick$3 adhes$3) near3 layer film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/30 13:07
-	2454602	chan et al.	USPAT; EPO	2002/07/30 15:26
-	9433	chan et al.	EPO	2002/07/30 15:28
-	0	(chan et al.) and 21/336	EPO	2002/07/30 15:28
-	1	"747941"	EPO	2002/07/30 15:37
-	1	"6294823"	USPAT	2002/07/30 15:37
-	1	"6307251"	USPAT	2002/07/30 15:38
-	1	10/085080	US-PGPUB	2002/11/08 08:42